AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A Group III nitride semiconductor multilayer structure comprising a substrate; an $Al_xGa_{1-x}N$ ($0 \leq x \leq 1$) buffer layer which is provided on the substrate and has a columnar or island-like crystal structure; and an $Al_xIn_yGa_{1-x-y}N$ ($0 \leq x \leq 1$, $0 \leq y \leq 1$, $0 \leq x + y \leq 1$) single-crystal layer provided on the buffer layer, wherein the substrate has, on its surface, non-periodically distributed scratches having an average depth of 0.01 to 5 μm.

2. (currently amended): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the ~~grooves~~ scratches have an average depth of 0.1 to 1 μm.

3. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the substrate is formed of sapphire single crystal or SiC single crystal.

4. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the buffer layer contains columnar crystal grains.

5. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the buffer layer has a thickness of 1 to 100 nm.

6. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the buffer layer is formed through continuously feeding of a Group III element source and a nitrogen source such that the ratio of nitrogen to a Group III element

becomes 1,000 or less, or through feeding of merely a Group III element source (in the case where the nitrogen/Group III element ratio is zero).

7. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the single-crystal layer has a thickness of 1 to 20 μm.

8. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the single-crystal layer is formed through feeding of a Group III element source and a nitrogen source such that the nitrogen/Group III element ratio becomes 1,600 to 3,200.

9. (previously presented): A Group III nitride semiconductor multilayer structure according to claim 1, wherein the single-crystal layer is formed while the temperature of the substrate is regulated so as to fall within a range of 1,000 to 1,300°C.

10. (original): A Group III nitride semiconductor multilayer structure according to claim 9, wherein the temperature of the substrate is regulated so as to fall within a range of 1,050 to 1,200°C.

11. (previously presented): A Group III nitride semiconductor light-emitting device comprising a Group III nitride semiconductor multilayer structure according to claim 1; Group III nitride semiconductor layers provided atop the single-crystal layer of the semiconductor multilayer structure, the semiconductor layers including an n-type layer, a light-emitting layer, and a p-type layer; and a negative electrode and a positive electrode which are provided at predetermined positions.

12. (original): A Group III nitride semiconductor light-emitting device according to claim 11, wherein the n-type layer, the light-emitting layer, and the p-type layer, which constitute the Group III nitride semiconductor layers, are successively provided atop the single-crystal

layer in this order; the negative electrode is provided on the n-type layer; and the positive electrode is provided on the p-type layer.

13. (canceled).

14. (canceled).

15. (canceled).

16. (withdrawn): A method for producing a Group III nitride semiconductor multilayer structure, said Group III nitride semiconductor multilayer structure comprising a substrate; an $Al_xGa_{1-x}N$ ($0 \leq x \leq 1$) buffer layer which is provided on the substrate and has a columnar or island-like crystal structure; and an $Al_xIn_yGa_{1-x-y}N$ ($0 \leq x \leq 1$, $0 \leq y \leq 1$, $0 \leq x + y \leq 1$) single-crystal layer provided on the buffer layer, wherein the substrate has, on its surface, non-periodically distributed scratches having an average depth of 0.01 to 5 μm, said method comprising a step of forming an $Al_xGa_{1-x}N$ ($0 \leq x \leq 1$) buffer layer by feeding, onto a heated substrate which has, on its surface, non-periodically distributed scratches having an average depth of 0.01 to 5 μm, a Group III element source and a nitrogen source such that the ratio of nitrogen to a Group III element becomes 1,000 or less, or by feeding, onto the substrate, merely a Group III element source (in the case where the nitrogen/Group III element ratio is zero); and subsequently a step of vapor-growing an $Al_xIn_yGa_{1-x-y}N$ ($0 \leq x \leq 1$, $0 \leq y \leq 1$, $0 \leq x + y \leq 1$) single-crystal layer atop the buffer layer by use of a Group III element source and a nitrogen source.

17. (withdrawn): A method for producing a Group III nitride semiconductor multilayer structure, said Group III nitride semiconductor multilayer structure comprising a substrate; an $Al_xGa_{1-x}N$ ($0 \leq x \leq 1$) buffer layer which is provided on the substrate and has a

columnar or island-like crystal structure; and an $Al_xIn_yGa_{1-x-y}N$ ($0 \leq x \leq 1$, $0 \leq y \leq 1$, $0 \leq x + y \leq 1$) single-crystal layer provided on the buffer layer, wherein the substrate has, on its surface, non-periodically distributed scratches having an average depth of 0.01 to 5 μm, said method comprising a buffer layer formation step in which a Group III element source and a nitrogen source are fed onto a substrate having, on its surface, non-periodically distributed scratches having an average depth of 0.01 to 5 μm while the temperature of the substrate is maintained at 400 to 600°C, to thereby form an $Al_xGa_{1-x}N$ ($0 \leq x \leq 1$) layer, and subsequently feeding of the Group III element source is stopped, followed by thermal treatment at 900 to 1,000°C; and subsequently a step of vapor-growing an $Al_xIn_yGa_{1-x-y}N$ ($0 \leq x \leq 1$, $0 \leq y \leq 1$, $0 \leq x + y \leq 1$) single-crystal layer atop the buffer layer by use of a Group III element source and a nitrogen source.